

Abstract

A method and apparatus for printed circuit board pads with registering feature for component leads. A U-shaped metalized pad is disposed on a printed circuit board for soldering to a component lead. Solder is disposed on the pad and heated to a molten state so that surface tension and wetting effects form the molten solder into a solder mound having a U-shaped lateral cross section conforming to the U-shaped metalized pad. The solder mound has a first arm and a second arm, and a lateral aperture extending therebetween for receiving an extremity of the component lead, and registering the extremity of the component lead with respect to the pad.